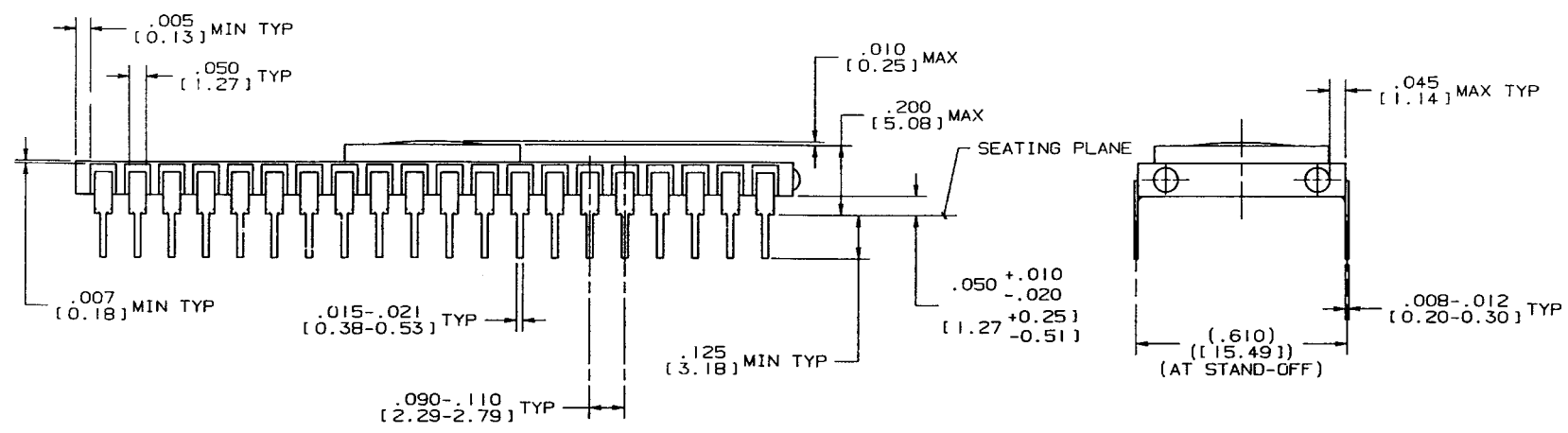
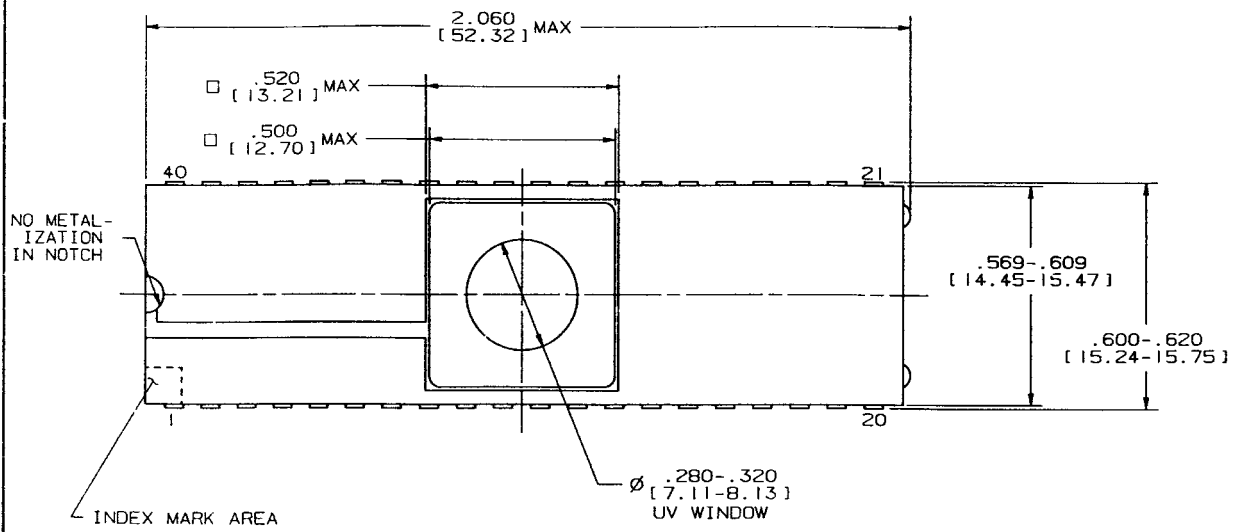


REVISIONS			
LTR	DESCRIPTION	E.C.N.	DATE
A	RELEASE TO DOCUMENT CONTROL	08262	11/27/90



NOTES: UNLESS OTHERWISE SPECIFIED

- LEAD FINISH TO BE ONE OF THE FOLLOWING:
 - 200 MICROINCHES/5.08 MICROMETERS MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
 - 200 TO 800 MICROINCHES/5.08 TO 20.32 MICROMETERS TIN PLATE OVER 50 TO 350 MICROINCHES/1.27 TO 8.89 MICROMETERS NICKEL UNDERPLATE OR BASIS METAL.
 - 50 TO 100 MICROINCHES/1.27 TO 2.54 MICROMETERS GOLD OVER 50 TO 350 MICROINCHES/1.27 TO 8.89 MICROMETERS NICKEL UNDERPLATE.
- LEAD FINISH, NICKEL UNDERPLATE AND BASIS METAL SHALL CONFORM TO THE REQUIREMENTS OF MIL-M-38510.

CONTROLLING DIMENSION: INCH					
DRAWN PAMELA GIFFORD	DATE 11/27/90	NATIONAL SEMICONDUCTOR CORPORATION 2900 Semiconductor Drive, Santa Clara, CA 95052-8090			
DETG. CHK. Marta S. [Signature]	11/29/90	HERMETIC DIP(D), 40 LEAD, EPROM			
ENGR. CHK. [Signature]	11/28/90				
APPROVAL		SCALE N/A	SIZE C	DRAWING NUMBER MKT-D40KQ	REV A
		FORMERLY: N/A	SHEET 1 OF 1		